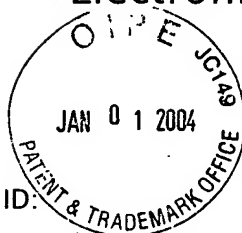


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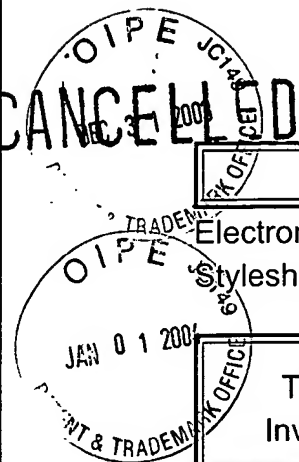


EFS ID: 53029  
Application ID: 10605059  
Title of Invention: METHOD OF FORMING A HIGHLY  
THERMALLY CONDUCTIVE AND  
HIGH STRENGTH ARTICLE  
First Named Inventor: Kevin McCULLOUGH  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2003-09-05  
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Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 2058  
Attorney Docket Number: C001P00472US2



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**TRANSMITTAL**

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of  
Invention

METHOD OF FORMING A HIGHLY THERMALLY CONDUCTIVE  
AND HIGH STRENGTH ARTICLE

Application Number: 10/605059  
Date: 2003-09-05  
First Named Applicant: Mr. Kevin A. McCULLOUGH



Confirmation Number: 2058  
Attorney Docket Number: C001P00472US2

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Mr. David R. Josephs Registered Number: 34,632	/david r. josephs/	Attorney

Documents being submitted  
us-ids

Files  
P0472US2-usidst.xml  
us-ids.dtd  
us-ids.xsl

Comments

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

<b>Title of Invention</b>	<b>METHOD OF FORMING A HIGHLY THERMALLY CONDUCTIVE AND HIGH STRENGTH ARTICLE</b>
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Application Number: 10/605059


Confirmation Number: 2058

First Named Applicant: Kevin McCULLOUGH

Attorney Docket Number: C001P00472US2

Art Unit: 1714

Search string: ( 3398233 or 3673121 or 3708387 or 4098945  
or 4307147 or 4367745 or 4496475 or 4568592  
or 4664971 or 4689250 or 4816184 or 5011870  
or 5011872 or 5021494 or 5098610 or 5098611  
or 5106540 or 5171774 or 5180513 or 5183594  
or 5213715 or 5225110 or 5286416 or 5302456  
or 5334330 or 5373046 or 5397608 or 5445308  
or 5490319 or 5522962 or 5536568 or 5580493  
or 5669381 or 5681883 or 5770305 or 5834337  
or 5851644 or 5863467 or 5945217 or 6048919  
or 6251978 or 6251978 or 6303096 or 5037590  
or 5552214 or 20020025998 or  
20020022686 ).pn.



### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	3673121	1972-06-27	Meyer		252	511
	3	3708387	1973-01-02	Turner et al			
	4	4098945	1978-07-04	Oehmke		428	327
	5	4307147	1981-12-22	Ohishi et al.		428	268
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	7	4496475	1985-01-29	Abrams		252	514
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	11	4816184	1989-03-28	Fukuda et al.		252	511
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

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	1	20020025998	2002-02-28	McCullough	A1	524	66
	2	20020022686	2002-02-21	Itoh et al.	A1	524	504

Signature

Examiner Name	Date